CLAIMS

1. An adhesive film comprising:

a base material layer;

an adhesive resin layer (A) provided on a first surface side of the base material layer; and

an adhesive resin layer (B) provided on a second surface side of the base material layer and in which an adhesive force is decreased by an external stimulus,

wherein the adhesive resin layer (A) includes an adhesive resin (A1), and the adhesive resin (A1) is at least one selected from a (meth)acrylic adhesive resin, a urethane-based adhesive resin, an olefin-based adhesive resin, and a styrene-based adhesive resin, and

wherein, as measured by method 1, an integrated tacking force value ($F_{2.5}$) of the adhesive resin layer (B) is 1.0 gf/sec or more at a test speed of 2.5 mm/min and a test temperature of 130°C, and an integrated tacking force value (F_{30}) of the adhesive resin layer (B) is 7.0 gf/sec or more at a test speed of 30 mm/min and a test temperature of 130°C,

(method 1) using a tacking tester, a probe is pressed on the adhesive resin layer (B) for 60 seconds under conditions of a probe load of 100 gf and a probe pushing speed of 120 mm/min, then, at a test temperature of 130°C, tack strengths (gf) are respectively measured at test speeds of 2.5 mm/min and 30 mm/min, a measurement time is set as a horizontal axis and the tack strength (gf) is set as a vertical axis, integrated values are each calculated from a point where the tack strength starts to rise from 0 to a point where the tack strength becomes 0 again, and the

calculated values are respectively set as $F_{2.5}$ and F_{30}.

2. The adhesive film according to claim 1,

wherein the adhesive film is used for temporarily fixing an electronic component when the electronic component is sealed with a sealing material in an electronic device manufacturing step.

3. The adhesive film according to claim 1 or 2,

wherein an adhesive force of the adhesive resin layer (B) is decreased by heating at a temperature over 150°C.

4. The adhesive film according to claim 3,

wherein the adhesive resin layer (B) includes at least one selected from a gas generating component and a heat-expandable microsphere.

5. The adhesive film according to ~~any one of claims~~claim 1 ~~to 4~~or 2,

wherein a content of at least one selected from a gas generating components and a heat-expandable microsphere in the adhesive resin layer (A) is 0.1% by mass or less when an entire adhesive resin layer (A) is 100% by mass.

6. The adhesive film according to ~~any one of claims~~claim 1 ~~to 5~~or 2,

wherein the adhesive resin layer (A) includes a (meth)acrylic adhesive resin.

~~7.~~

7. The adhesive film according to claim 1 or 2,

wherein the adhesive resin layer (B) includes an adhesive resin (B1) and a cross-linking agent (B2).

8. The adhesive film according to claim 7,

wherein the content of the cross-linking agent (B2) is 0.5 parts by mass or more and 4.0 parts by mass or less with respect to 100 parts by mass of the adhesive resin (B1).

9. The adhesive film according to claim 7,

wherein the adhesive resin (B1) includes 10% by mass or more and 98.9% by mass or less of a (meth)acrylic acid alkyl ester monomer unit (b1) and 1% by mass or more and 40% by mass or less of a monomer unit (b2) having a functional group capable of reacting with the cross-linking agent (B2) with respect to 100% by mass of the total of all the monomer units.

10. The adhesive film according to claim 7,

wherein the cross-linking agent (B2) is at least one selected from epoxy-based compounds, isocyanate-based compounds, aziridine-based compounds, and melamine-based compounds.

11. A method for manufacturing an electronic device comprising at least:

a step (1) of preparing a structure having the adhesive film according to ~~any one of claims~~claim 1 ~~to 6~~or 2, an electronic component attached to the adhesive resin layer (A) of the adhesive film, and a support substrate attached to the adhesive resin layer (B) of the adhesive

film;

a step (2) of sealing the electronic component with a sealing material;

a step (3) of peeling the support substrate from the structure by decreasing an adhesive force of the adhesive resin layer (B) by applying an external stimulus; and

a step (4) of peeling the adhesive film from the electronic component.

~~8~~12. The method for manufacturing an electronic device according to claim ~~7~~11,

wherein the sealing material is an epoxy resin-based sealing material.